

**IN THE CLAIMS**

Please amend the claims as follows:

Claim 1 (currently amended): A composite magnetic material comprising:

a resin; and

generally spherical magnetic metal particles of at least one type dispersed in the resin and consisting essentially of single crystal grains, the metal particles having a mean particle size of 0.1 to 10  $\mu\text{m}$  and ~~coated over at least a part of their surface with~~ each having an insulating coating layer at least partially coated thereon, ~~the coated metal particles being~~ dispersed in a resin.

Claim 2 (currently amended): The composite magnetic material of claim 1 wherein said insulating coating layer has a thickness of 0.005 to 5  $\mu\text{m}$ .

Claim 3 (original): The composite magnetic material of claim 1 wherein 30 to 98% by weight of said coated metal particles are dispersed in said resin.

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Claim 4 (original): A magnetic molding material comprising the composite magnetic material of claim 1.

Claim 5 (original): A magnetic powder compression molding material comprising the composite magnetic material of claim 1 wherein 90 to 98% by weight of said coated metal particles are dispersed in said resin.

Claim 6 (original): A magnetic paint comprising the composite magnetic material of claim 1.

Claim 7 (original): A prepreg comprising the composite magnetic material of claim 1.

Claim 8 (original): A prepreg comprising the composite magnetic material of claim 1 and a glass cloth embedded therein.

Claim 9 (original): The prepreg of claim 7 further comprising a copper foil clad thereto.

Claim 10 (original): A magnetic substrate comprising the composite magnetic material of claim 1 or the prepreg of claim 7.

Claim 11 (original): The magnetic substrate of claim 10 further comprising a copper foil clad thereto.

Claim 12 (currently amended): A composite dielectric material comprising:  
a resin; and  
generally spherical metal particles of at least one type dispersed in the resin and  
having a mean particle size of 0.1 to 10  $\mu\text{m}$ , ~~and coated over at least a part of their surface~~  
with the metal particles each having a dielectric coating layer at least partially coated thereon;  
~~the coated particles being dispersed in a resin.~~

Claim 13 (currently amended): The composite dielectric material of claim 12 wherein said dielectric coating layer has a thickness of 0.005 to 5  $\mu\text{m}$ .

Claim 14 (original): The composite dielectric material of claim 12 wherein said dielectric layer is formed of an oxide dielectric material having a higher dielectric constant than said resin.

Claim 15 (original): The composite dielectric material of claim 12 wherein said metal particles are formed of at least one metal selected from the group consisting of silver, gold, platinum, palladium, copper, nickel, iron, aluminum, molybdenum, tungsten, and alloys and mixtures thereof.

Claim 16 (currently amended): The composite dielectric material of claim 12 wherein said dielectric coating layer is formed of an oxide dielectric material having a higher dielectric constant than said resin.

Claim 17 (original): A molding material comprising the composite dielectric material of claim 12.

Claim 18 (original): A powder compression molding material comprising the composite dielectric material of claim 12 wherein 90 to 98% by weight of said coated metal particles are dispersed in said resin.

Claim 19 (original): A paint comprising the composite dielectric material of claim 12.

Claim 20 (original): A prepreg comprising the composite dielectric material of claim 12.

Claim 21 (original): A prepreg comprising the composite dielectric material of claim 12 and a glass cloth embedded therein.

Claim 22 (original): The prepreg of claim 20 further comprising a copper foil clad thereto.

Claim 23 (original): A substrate comprising the material of claim 12.

Claim 24 (original): The substrate of claim 23 further comprising a copper foil clad thereto.

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Claim 25 (currently amended): An electronic part comprising a composite dielectric material comprising a resin and generally spherical metal particles of at least one type dispersed in the resin and having a mean particle size of 0.1 to 10  $\mu\text{m}$ , ~~and coated over at least a part of their surface with~~ the metal particle each having a dielectric coating layer at least partially coated thereon, ~~the coated particles being dispersed in a resin.~~

Claim 26 (currently amended): The electronic part of claim 25 wherein said dielectric coating layer has a thickness of 0.005 to 2  $\mu\text{m}$ .

Claim 27 (currently amended): An electronic part comprising a composite material comprising a resin and generally spherical metal particles of at least one type dispersed in the resin and consisting essentially of single crystal grains, the metal particles having a mean particle size of 0.1 to 10  $\mu\text{m}$  and ~~coated over at least a part of their surface with~~ each having

an insulating coating layer at least partially coated thereon, ~~the coated metal particles being dispersed in a resin.~~

Claim 28 (currently amended): An electronic part comprising a composite material comprising a resin and generally spherical magnetic metal particles of at least one type dispersed in the resin and consisting essentially of single crystal grains, the metal particles having a mean particle size of 0.1 to 10  $\mu\text{m}$  and ~~coated over at least a part of their surface with each having an insulating coating layer at least partially coated thereon, the coated metal particles being dispersed in a resin.~~

Claim 29 (currently amended): The electronic part of claim 27 wherein said insulating coating layer has a thickness of 0.005 to 2  $\mu\text{m}$ .

Claim 30 (original): The electronic part of claim 25 comprising said composite dielectric material, said composite material or a combination of said composite dielectric material with said composite material.

Claim 31 (original): The electronic part of claim 25 wherein said composite dielectric material or said composite material includes at least one layer having a glass cloth embedded in a resin.

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